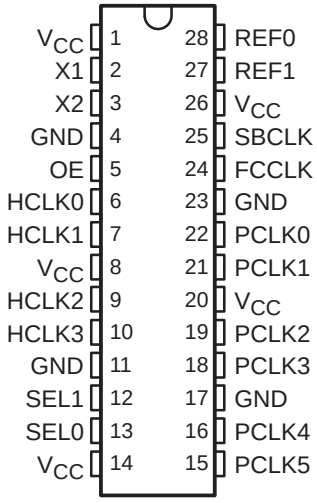
- **Provides System Clock Solution for Pentium™/82430HX/82430VX and Pentium Pro 82440FX Chipsets**
- **Four Host-Clock Outputs With Programmable Frequency (50 MHz, 60 MHz, and 66 MHz)**
- **Six PCI Clock Outputs at Half-CPU Frequency**
- **One 48-MHz Universal Serial Bus (USB) Clock Output**
- **One 24-MHz Floppy Controller Output**
- **Two 14.318-MHz Reference Clock Outputs**
- **All Output Clock Frequencies Derived From Single 14.31818-MHz Crystal Input**
- **LVTTL-Compatible Inputs and Outputs**
- **Internal Loop Filters for Phase-Lock Loops Eliminate the Need for External Components**
- **Operates at 3.3-V V_{CC}**
- **Packaged in Plastic Small-Outline Package**

DW PACKAGE
(TOP VIEW)



description

The CDC9843 is a high-performance clock synthesizer/driver that generates the system clocks necessary to support Pentium™/82430HX/82430VX and Pentium Pro 82440FX chipsets. Four host-clock outputs (HCLKn) are programmable to one of three frequencies (50 MHz, 60 MHz, or 66 MHz) via the SEL0 and SEL1 control inputs. Six PCI-clock outputs (PCLKn) are half the frequency of CPU clock outputs and are delayed 1 ns to 4 ns from the rising edge of the CPU clock. In addition, a universal serial bus (USB) clock output at 48 MHz (SBCLK), a floppy controller clock at 24 MHz (FCCLK), and two 14.318-MHz reference clock outputs (REF0, REF1) are provided.

All output frequencies are generated from a 14.318-MHZ crystal input. A reference clock input can be provided at the X1 input instead of a crystal input.

Two phase-locked loops (PLLs) are used to generate the host clock frequency and the 48-MHz clock frequency. On-chip loop filters and internal feedback eliminate the need for external components. The PCI-clock frequency and floppy controller frequency are derived directly from the host-clock frequency and USB frequency, respectively. The PLL circuit can be bypassed in the test mode (i.e., SEL0 = SEL1 = H) to distribute a test clock provided at the X1 input.

The host- and PCI-clock outputs provide low-skew/low-jitter clock signals for reliable clock operation. All outputs are 3 state and are enabled via OE.

Because the CDC9843 is based on PLL circuitry, it requires a stabilization time to achieve phase-lock of the PLL. This stabilization time is required following power up and application of a fixed-frequency, fixed-phase signal at the X1, as well as following any changes to the OE or SELn inputs.

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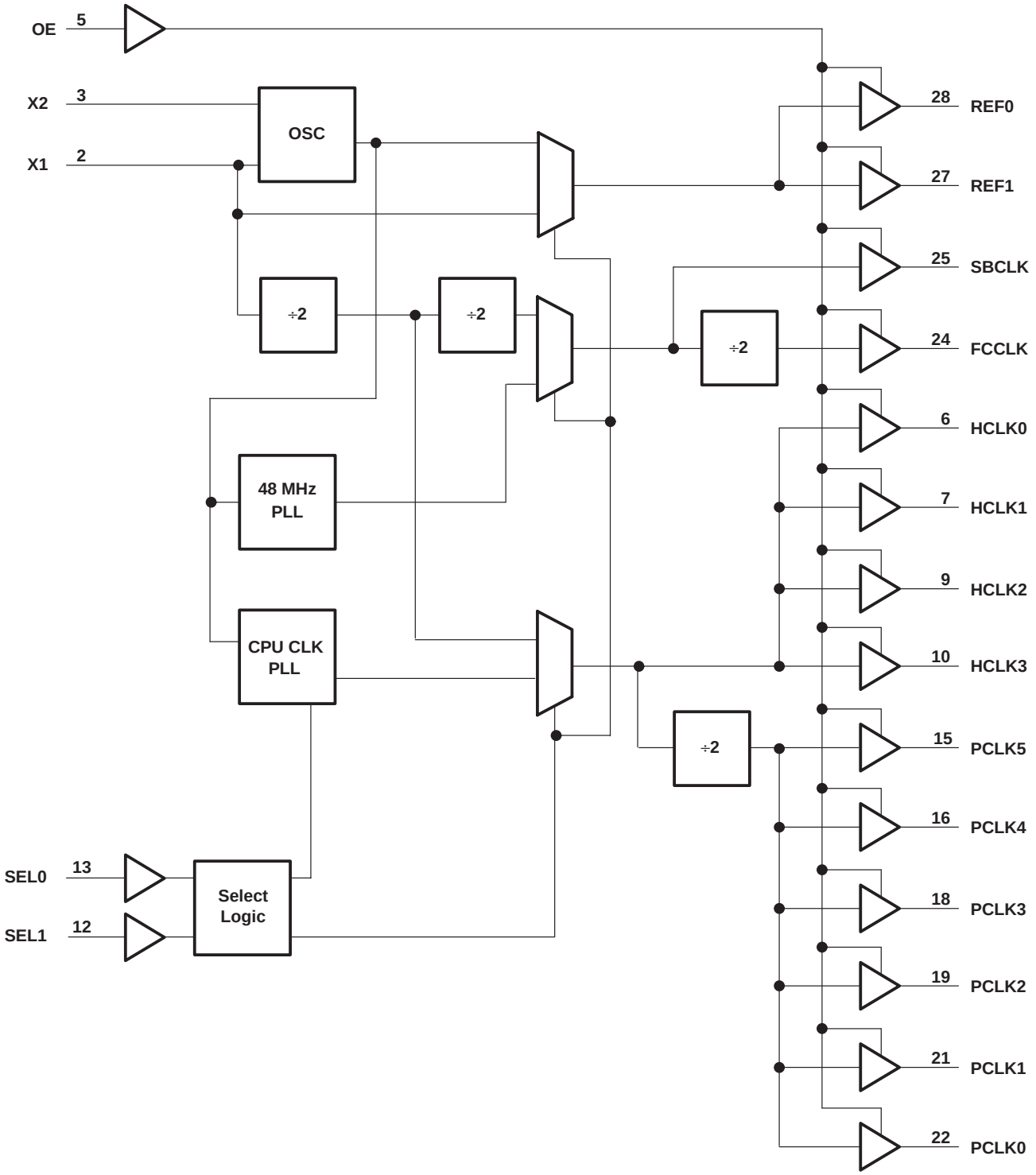
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FUNCTION TABLE

OE	SEL0	SEL1	X1	HCLKn	PCLKn	REFn	SBCLK	FCCLK
L	X	X	14.318 MHz	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z
H	L	L	14.318 MHz	50 MHz	25 MHz	14.318 MHz	48 MHz	24 MHz
H	L	H	14.318 MHz	60 MHz	30 MHz	14.318 MHz	48 MHz	24 MHz
H	H	L	14.318 MHz	66 MHz	33 MHz	14.318 MHz	48 MHz	24 MHz
H	H	H	TCLK†	TCLK/2	TCLK/4	TCLK	TCLK/4	TCLK/8

† TCLK is a test-clock input at the X1 input during test mode.

functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 4.6 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to 4.6 V
Voltage range applied to any output in the high-impedance state or power-off state,
V_O (see Note 1) . . . . . –0.5 V to V_{CC} + 0.5 V
Current into any output in the low state, I_O . . . . . 16 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . –18 mA
Output clamp current, I_{OK} (V_O < 0) . . . . . –50 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2) . . . . . TBD
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	3.135	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage	0	V_{CC}	V
I_{OH}	High-level output current		–8	mA
I_{OL}	Low-level output current		8	mA
T_A	Operating free-air temperature	0	70	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP‡	MAX	UNIT
V_{IK}	V_{CC} = 3.135 V,	I_I = –18 mA				–1.2	V
V_{OH}	V_{CC} = 3.135 V,	I_{OH} = –8 mA		2.5			V
V_{OL}	V_{CC} = 3.135 V,	I_{OL} = 8 mA				0.4	V
I_I	V_{CC} = 3.6 V,	V_I = V_{CC} or GND				±1	µA
I_{OZ}	V_{CC} = 3.6 V,	V_O = V_{CC} or GND				±10	µA
I_{CC}	V_{CC} = 3.6 V, V_I = V_{CC} or GND	I_O = 0,	Outputs enabled§			50	mA
			Outputs disabled			1	mA
C_i	V_I = V_{CC} or GND				6		pF
C_o	V_I = V_{CC} or GND				6		pF

‡ All typical values are at V_{CC} = 3.3 V.
§ Device in normal operating mode with no load on outputs

timing requirements over recommended ranges of supply voltage and operating free-air temperature

		MIN	MAX	UNIT
Stabilization time†	After SEL1, SEL0		5	ms
	After OE↑		5	
	After power up		5	

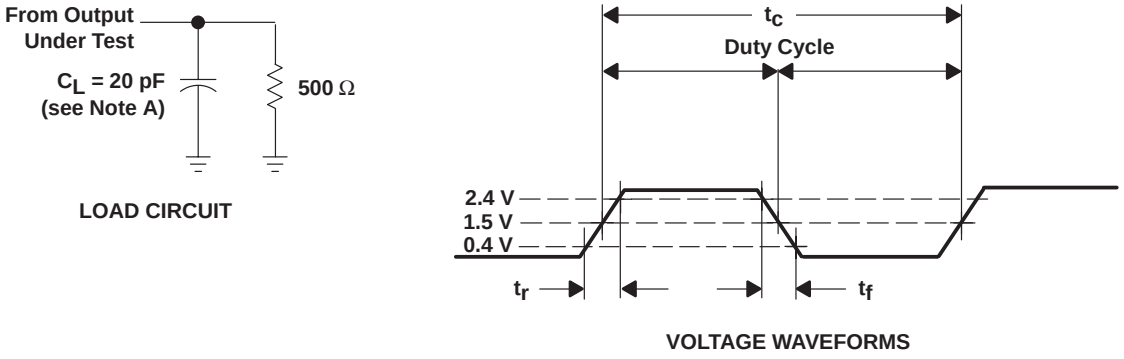
† Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. In order for phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at X1. Until phase lock is obtained, the specifications for propagation delay and skew parameters given in the switching characteristics table are not applicable.

switching characteristics (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		V_{CC} = 3.135 V to 3.6 V, T_A = 0°C to 70°C		UNIT
				MIN	MAX	
t_{Skew}‡		HCLKn			200	ps
		PCLKn			400	ps
Offset‡	HCLKn	PCLKn		1	4	ns
Jitter‡		HCKLn			±250	ps
		PCKLn			±350	ps
Duty cycle‡		Any output		45%	55%	
t_c‡		HCKLn	SEL0 = L, SEL1 = L	20		ns
			SEL0 = L, SEL1 = H	16.7		ns
			SEL0 = H, SEL1 = L	15		ns
		PCLKn	SEL0 = L, SEL1 = L	40		ns
			SEL0 = L, SEL1 = H	33.3		ns
			SEL0 = H, SEL1 = L	30		ns
t_r‡§		HCLKn			2	ns
		PCKLn				
t_f‡§		HCKLn			2	ns
		PCLKn				

‡ Specifications are applicable only after the PLL stabilization time has elapsed.
§ Rise and fall times are characterized using the load circuits shown in Figure 1.

PARAMETER MEASUREMENT INFORMATION
CLOCK DRIVER CIRCUITS



NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

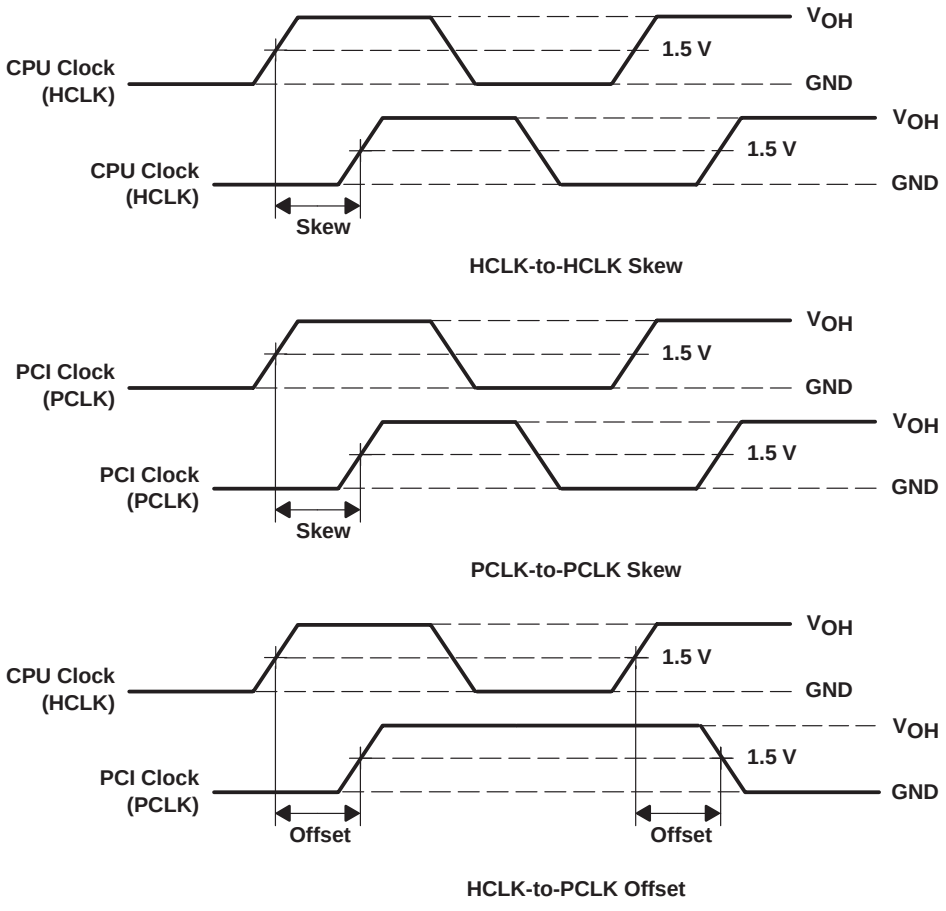


Figure 2. Waveforms for Calculation of t_{Skew} and t_{offset}

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CDC9843DW	OBSOLETE	SOIC	DW	28		TBD	Call TI	Call TI
CDC9843DWR	OBSOLETE	SOIC	DW	28		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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